

MALS068X

Silicon planar type

For constant voltage and surge absorption circuits

■ Features

- Bi-directional and high electrostatic discharge ESD
- Small terminal capacitance C_t

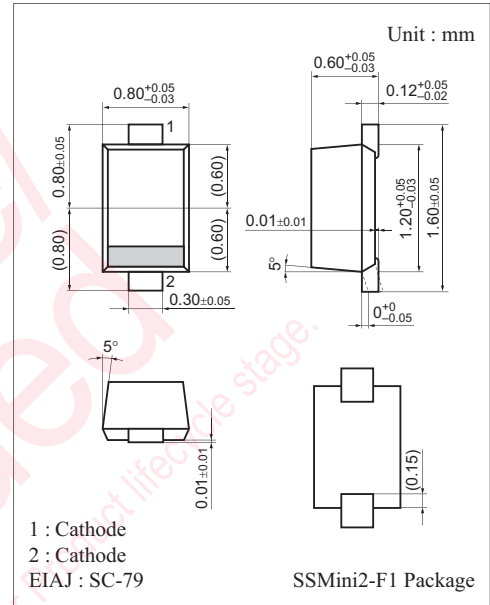
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *1	P_T	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$
Electrostatic discharge *2	ESD	± 15	kV

Note) *1: $P_T = 150$ mW achieved with a printed circuit board.

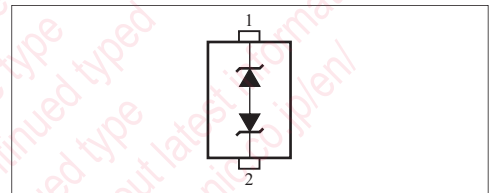
*2: Test method: IEC61000-4-2

($C = 150$ pF, $R = 330 \Omega$, Contact discharge: 10 times)



Marking Symbol: RX

Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *	V_Z	$I_Z = 5$ mA	6.5	7.0	7.5	V
Zener operating resistance	R_Z	$I_Z = 5$ mA			20	Ω
Reverse current	I_R	$V_R = 4.0$ V			50	nA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		15		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. The temperature must be controlled 25°C for V_Z measurement.

V_Z value measured at other temperature must be adjusted to $V_Z (25^\circ\text{C})$

3. *: V_Z guaranteed 20 ms after current flow.

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